

(1.27 mm) .050"

SEAM SERIES

HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Operating Temp Range:

-55°C to +125°C

Current Rating

(7 mm stack height):

1.8 A per pin

(10 adjacent pins powered)

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Contact Resistance: 5.5 mΩ

Working Voltage: 240 VAC

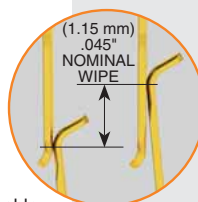
RoHS Compliant: Yes

Lead-Free Solderable: Yes

Mates with:
SEAF, SEAFP

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.



Low insertion/extraction forces

Up to 500 Pins

5, 8 and 10 row footprint compatible with SamArray®. Samples recommended.

Solder charges

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Industry Standards

PISMO 2

VITA 47

VITA 57

Protocols Supported

100 GbE

Fibre Channel

Rapid I/O

PCI Express®

SATA

InfiniBand™

Download app notes at:

www.samtec.com/appnote

Contact SIG @ samtec.com

for questions on protocols

MATED HEIGHTS			
SEAM LEAD STYLE	SEAF LEAD STYLE	-05.0	-06.0
-02.0	7 mm	8 mm	8.5 mm
-03.0	8 mm	9 mm	9.5 mm
-03.5	8.5 mm	9.5 mm	10 mm
-06.5	11.5 mm	12.5 mm	13 mm
-07.0	12 mm	13 mm	13.5 mm
-09.0	14 mm	15 mm	15.5 mm
-11.0	16 mm	17 mm	17.5 mm

SEAM/SEAF 10 mm Stack Height	Rated @ 3dB Insertion Loss w/o PCB effects*
Single-Ended Signaling	18 GHz / 36 Gbps
Differential Pair Signaling	18 GHz / 36 Gbps

*Test board losses de-embedded from performance data.
Performance data for other stack heights and complete test data available at www.samtec.com?SEAM or contact sig@samtec.com

SEAM	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	TR
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-10, -15, -20, -30, -40, -50
(-10 only available in 04 row)
(-15 only available in 10 row)

Specify LEAD STYLE from chart

NO. OF ROWS	B
-04	(7.06) .278
-05, -06	(9.60) .378
-08	(12.14) .478
-10	(14.68) .578

-L
= 10 μ" (0.25 μm)
Gold on contact area, Matte Tin on solder tail

-S
= 30 μ" (0.76 μm)
Gold on contact area, Matte Tin on solder tail

-04
= Four Rows (-06.5 not available)

-05
= Five Rows (-06.5 not available)

-06
= Six Rows (-06.5 not available)

-08
= Eight Rows

-10
= Ten Rows

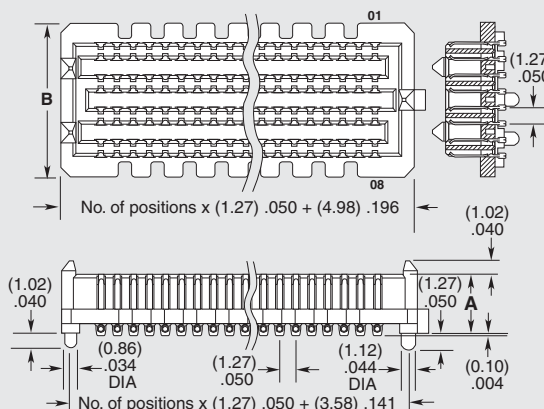
-1
= Tin/Lead Alloy Solder Charge

-2
= Lead-Free Solder Charge

-A
= Alignment Pins (Required. Arrays will not self-center on solder pads)

-K
= Polyimide film Pick & Place Pad

-TR
= Tape & Reel



LEAD STYLE	A
-02.0	(4.60) .181
-03.0	(5.59) .220
-03.5	(6.10) .240
-06.5	(9.14) .360
-07.0	(9.60) .378
-09.0	(11.60) .457
-11.0	(13.60) .535

DIFFERENTIAL

ARRAY	PAIR COUNT
40x8	80
40x6	60
30x10	75
30x8	60
30x6	45
20x10	50
20x8	40
20x5	25